

60V 3mohm N-channel SGT MOSFET SI003N06NG2

Description:

This N channel SGT MOSFET has been designed to very low on-state resistance and maintain superior switching performance, especial for high efficiency power management applications.

Features:

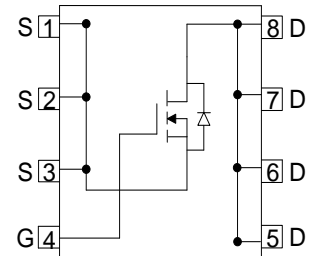
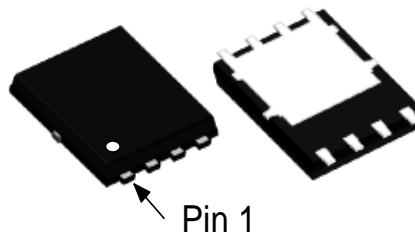
- Low $R_{DS(ON)}$
- RoHS compliant ^(Note 1)
- Halogen-free ^(Note 1)

Applications:

- Battery Management System
- Motor Drivers
- DC-DC Converter

Key Performance Parameters:

| Parameter | Value | Unit |
|----------------------------------|-------|------------|
| V_{DS} | 60 | V |
| $R_{DS(ON), max} @ V_{GS} = 10V$ | 3.0 | m Ω |
| I_D | 120 | A |



Ordering Information:

| Ordering Code | Package Type | Marking Code | Form | Packing |
|---------------|--------------|--------------|-----------|---------|
| SI003N06NG2 | DFN5X6 | SI003N06NG2 | Tape Reel | 5000PCS |

Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Value | Units |
|----------------|---|-------------|------------------|
| V_{DS} | Drain-Source Voltage | 60 | V |
| I_D | Drain Current - Continuous ($T_C = 25^\circ\text{C}$) ^(Note 1) | 120 | A |
| | Drain Current - Continuous ($T_C = 100^\circ\text{C}$) | 98 | A |
| I_{DM} | Drain Current - Pulsed ^(Note 2) | 400 | A |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| E_{AS} | Single Pulsed Avalanche Energy ^(Note 3) | 196 | mJ |
| P_D | Power Dissipation ($T_C = 25^\circ\text{C}$) | 62 | W |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 to +150 | $^\circ\text{C}$ |

Thermal Characteristics

| Symbol | Parameter | Value | Units |
|-----------------|---|-------|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case, Steady-State | 2 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient, Steady State ^(Note 4) | 61 | $^\circ\text{C}/\text{W}$ |

Notes:

1. The max drain current rating is package limited
2. Repetitive Rating: Pulse width limited by maximum junction temperature
3. $L = 0.5 \text{ mH}$, $V_{DD} = 30 \text{ V}$, $I_{AS} = 28 \text{ A}$, $R_G = 25 \text{ } \Omega$, Starting $T_J = 25 \text{ } ^\circ\text{C}$
4. Mount on minimum PCB layout

| Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted) | | | | | | |
|--|---|---|-----|------|------|---------------|
| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
| Static Characteristics | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$ | 60 | | | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V},$ | | 0.5 | 1 | μA |
| I_{GSS} | Gate Leakage Current | $V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$ | | 10 | 100 | nA |
| $V_{GS(TH)}$ | Gate Threshold voltage | $V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$ | 1 | 2 | 3 | V |
| $R_{DS(ON)}$ | Drain-Source on-state resistance | $V_{GS} = 10\text{ V}, I_D = 20\text{ A}$ | | 2.6 | 3.0 | m Ω |
| | | $V_{GS} = 4.5\text{ V}, I_D = 15\text{ A}$ | | 4.1 | 5.2 | m Ω |
| Dynamic Characteristics | | | | | | |
| C_{ISS} | Input Capacitance | $V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V},$ $F = 1\text{ MHz}$ | | 3200 | 4200 | pF |
| C_{OSS} | Output Capacitance | | | 773 | 890 | pF |
| C_{RSS} | Reverse Transfer Capacitance | | | 50 | 78 | pF |
| R_G | Gate Resistance | $F = 1\text{ MHz}$ | | 1.1 | 1.95 | Ω |
| Switching Characteristics | | | | | | |
| $T_{D(ON)}$ | Turn On Delay Time | $V_{DD} = 30\text{ V}, R_L = 1.5\ \Omega,$ $V_{GS} = 10\text{ V}, R_G = 6\ \Omega$ | | 18 | | nS |
| T_R | Rise Time | | | 51.0 | | nS |
| $T_{D(OFF)}$ | Turn Off Delay Time | | | 61.0 | | nS |
| T_F | Fall Time | | | 65.5 | | nS |
| Q_G | Total Gate Charge | $V_{DD} = 30\text{ V}, I_D = 20\text{ A},$ $V_{GS} = 10\text{ V}$ | | 69.2 | | nC |
| Q_{GS} | Gate-Source Charge | | | 11.7 | | nC |
| Q_{GD} | Gate-Drain Charge | | | 17.8 | | nC |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I_S | Maximum Continuous Body-Diode Forward Current | | | 120 | | A |
| I_{SM} | Maximum Pulsed Body-Diode Forward Current ^(NOTE 1) | | | 400 | | A |
| V_{SD} | Diode Forward Voltage | $V_{GS} = 0\text{ V}, I_S = 1\text{ A}$ | | 0.7 | 1 | V |
| T_{RR} | Reverse recovery time | $V_{DD} = 30\text{ V}, I_D = 20\text{ A},$ $di/dt = 100\text{ A}/\mu\text{S}$ | | 44.5 | | nS |
| Q_{RR} | Reverse recovery charge | | | 52.0 | | nC |
| I_{RRM} | Peak Reverse Recovery Current | | | 2 | | A |

Electrical Characteristics Diagrams

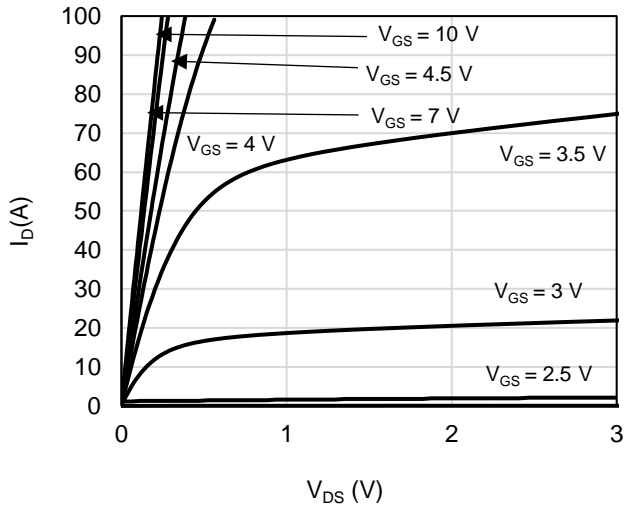


Figure 1: On-Region Characteristics

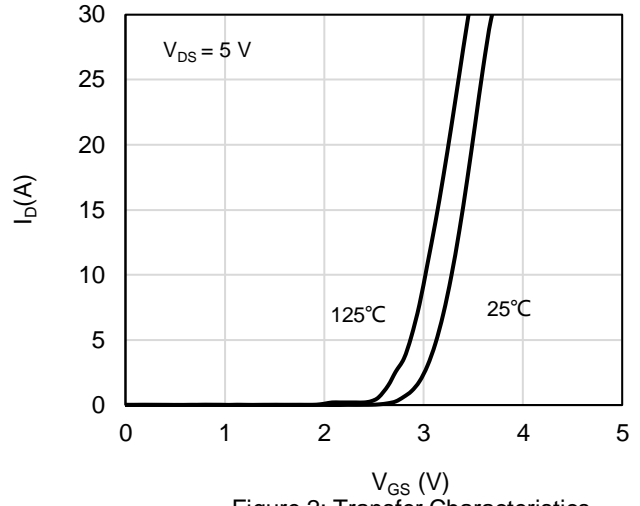


Figure 2: Transfer Characteristics

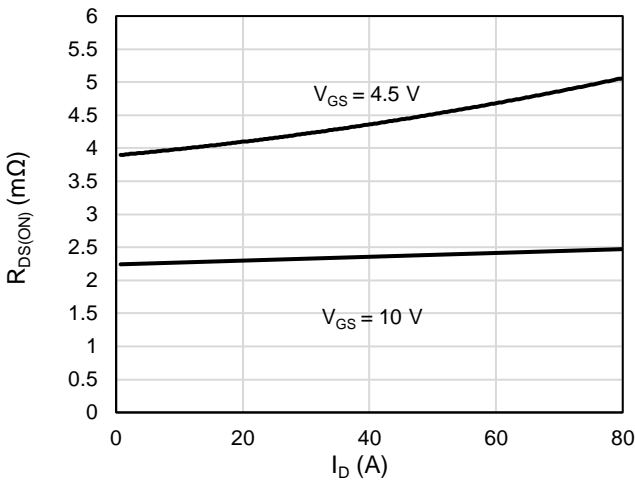


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

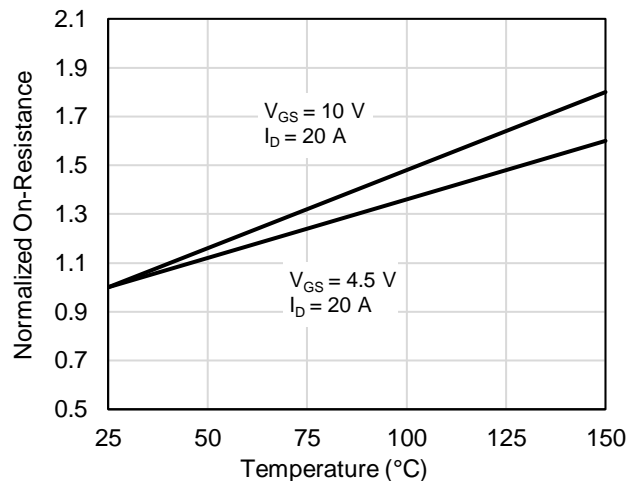


Figure 4: On-Resistance vs. Junction Temperature

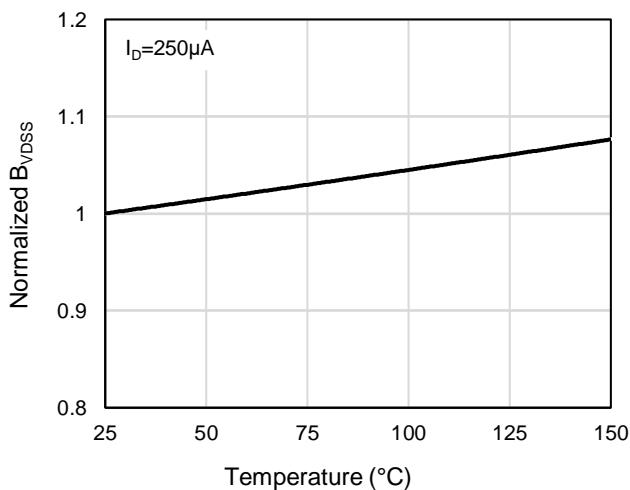


Figure 5: Breakdown Voltage vs. Junction Temperature

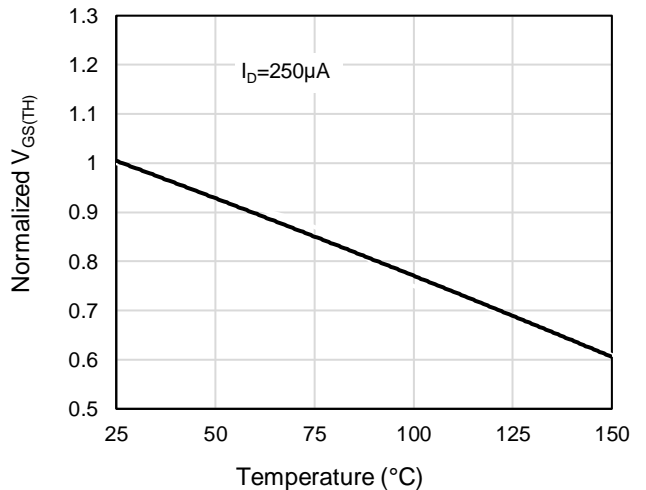
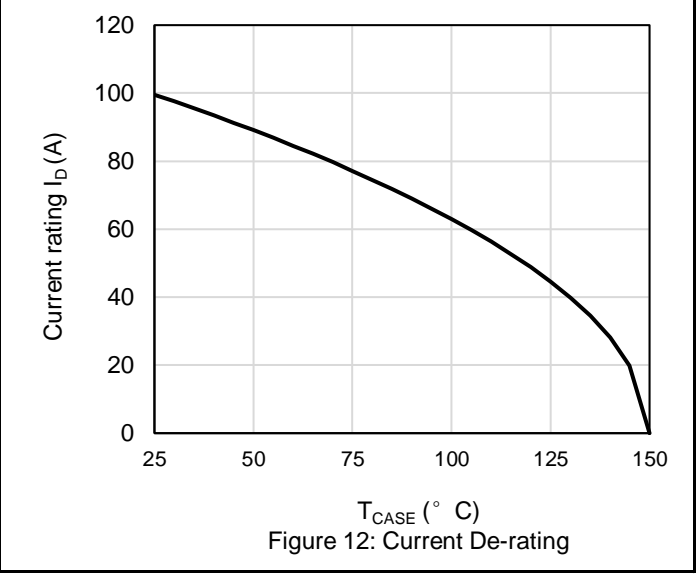
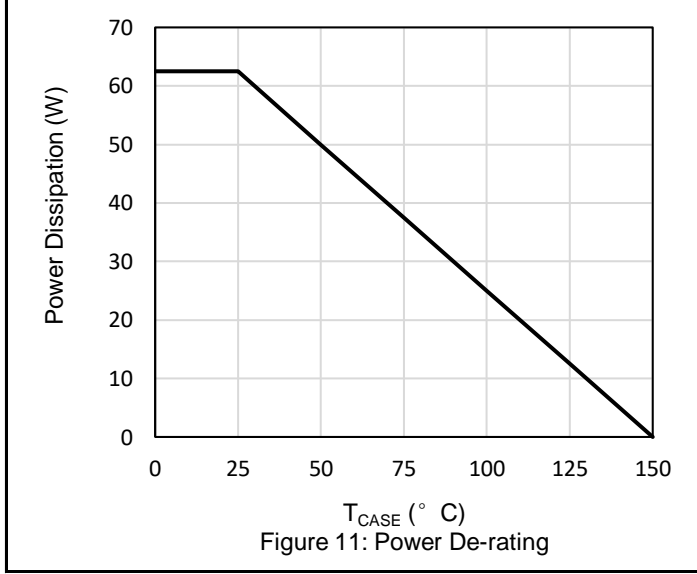
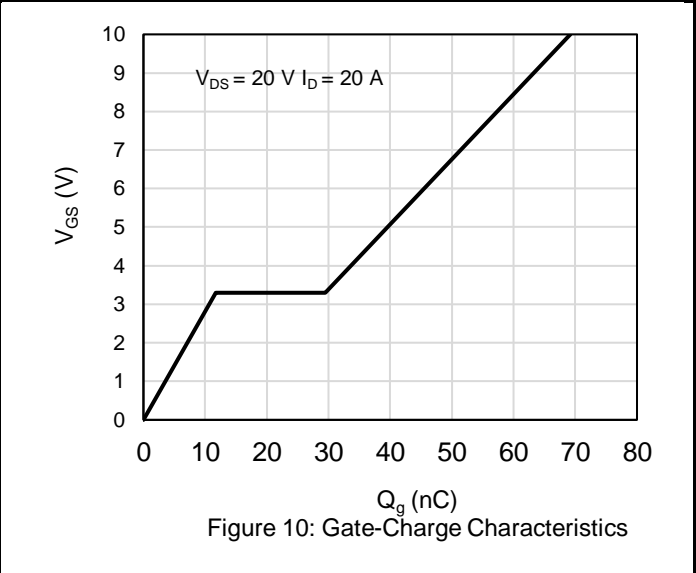
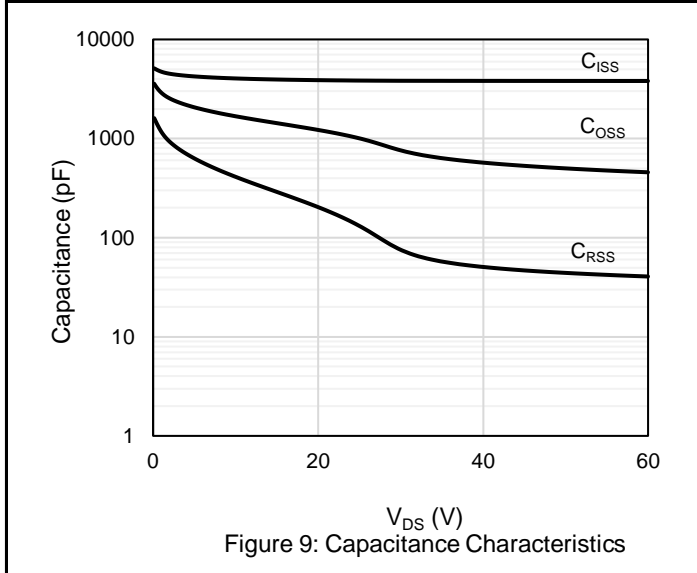
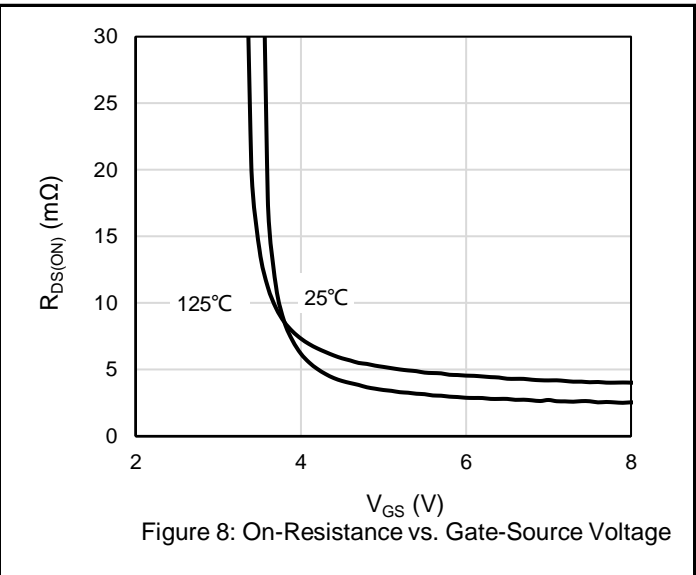
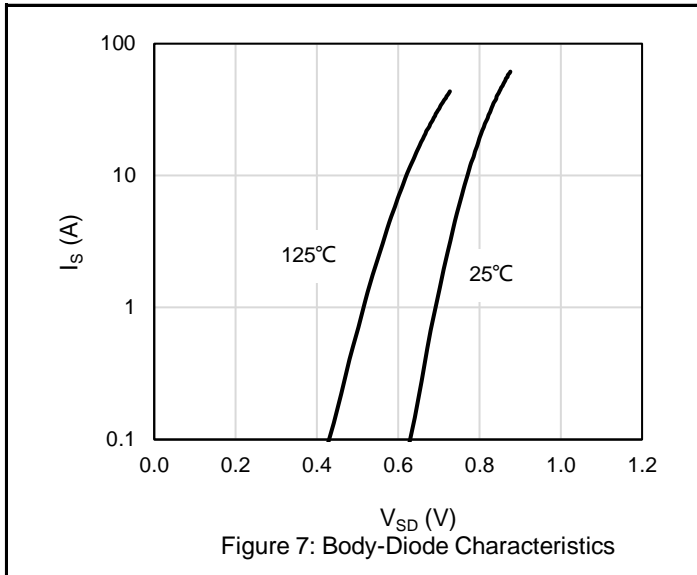
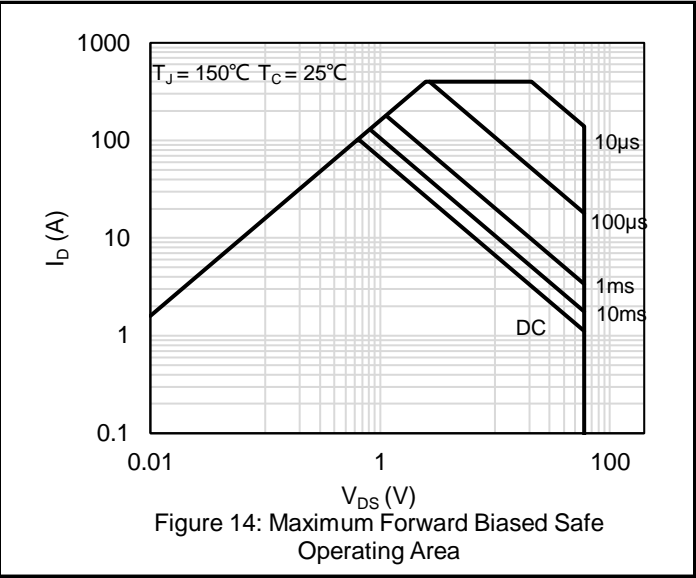
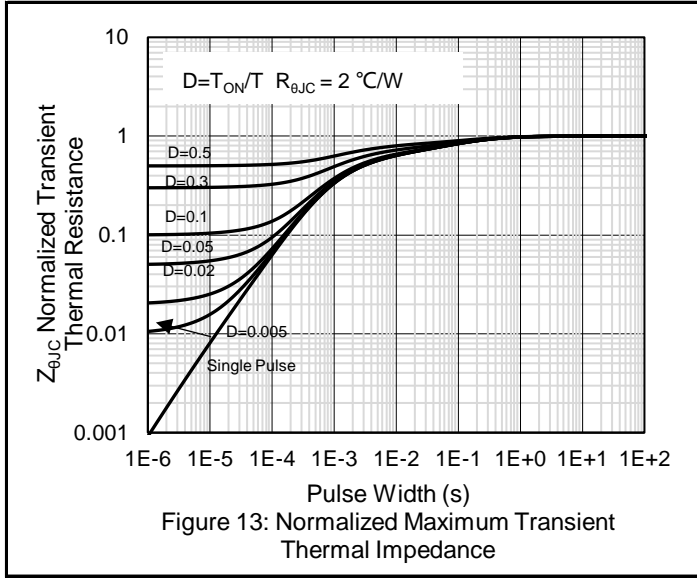


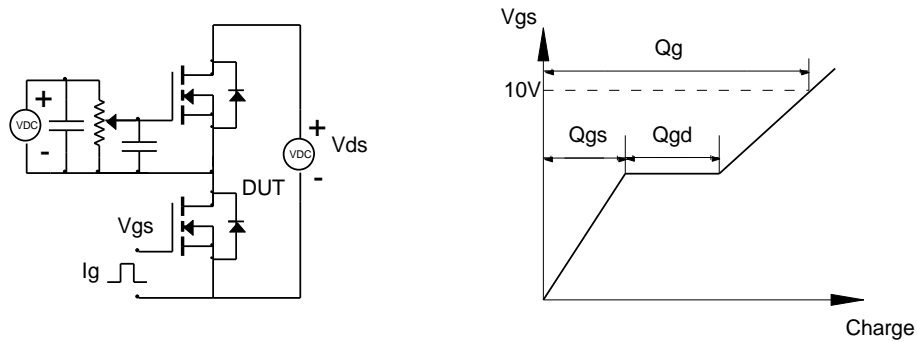
Figure 6: Threshold Voltage vs. Junction Temperature



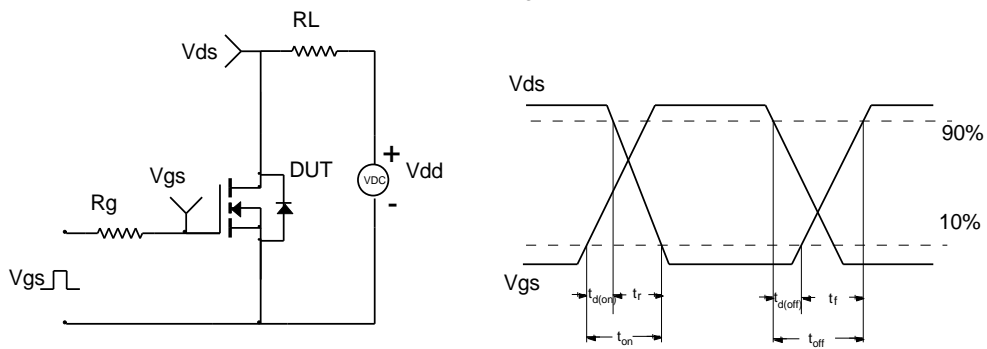


Test Circuit and Waveform

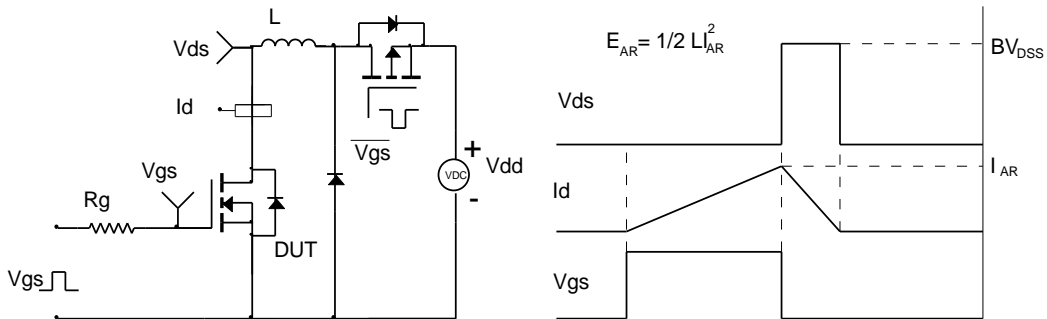
Gate Charge Test Circuit & Waveform



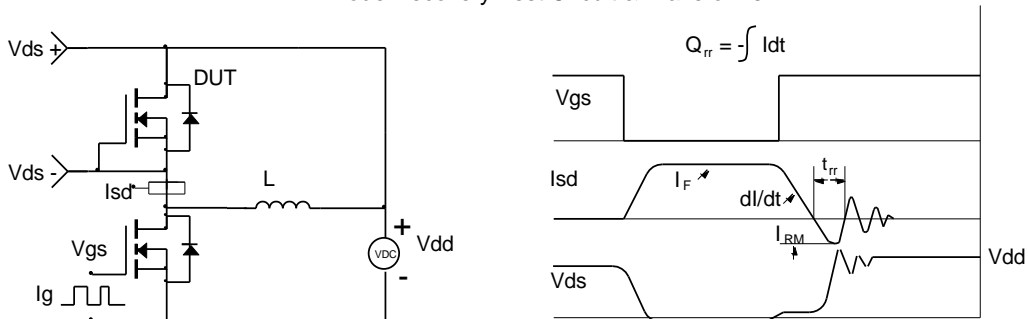
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



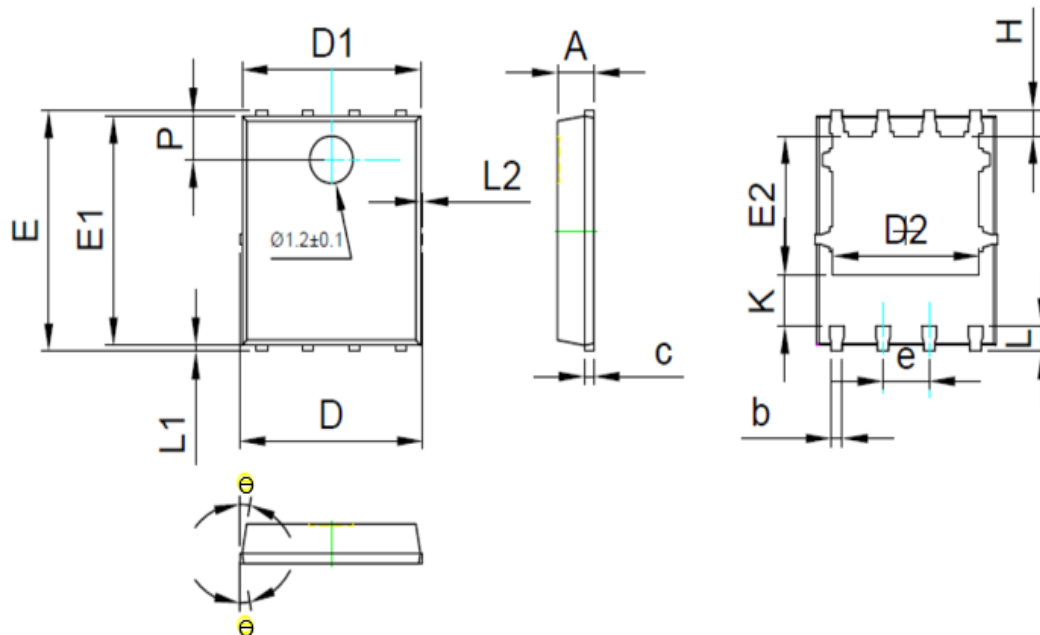
Diode Recovery Test Circuit & Waveforms



Package Outlines

Package Dimensions : DFN 5*6 PACKAG

E



COMMON DIMENSIONS
(UNITS OF MEASURE = MILLIMETER)

| SYMBOL | MIN | NOM | MAX |
|----------|----------|-------|-------|
| A | 0.90 | 1.00 | 1.10 |
| b | 0.35 | 0.40 | 0.45 |
| c | 0.21 | 0.25 | 0.34 |
| D | - | - | 5.1 |
| D1 | 4.85 | 4.90 | 4.95 |
| D2 | 3.96 | 4.01 | 4.06 |
| e | 1.27 BSC | | |
| E | 5.95 | 6.00 | 6.05 |
| E1 | 5.70 | 5.75 | 5.80 |
| E2 | 3.425 | 3.475 | 3.525 |
| H | 0.60 | 0.65 | 0.70 |
| K | 1.29 | - | - |
| L | 0.60 | 0.65 | 0.70 |
| L1 | 0.05 | 0.15 | 0.25 |
| L2 | - | - | 0.12 |
| θ | 8° | 10° | 12° |
| P | 1.05 | 1.10 | 1.15 |